

# Y-201TSR / Y-201TSRP

## High Tg, White Laminate & Prepreg for IC Packages

### 产品特点:

- 无卤, Tg200°C (DMA)
- 高白度、高反射率
- 优异的耐黄变性能
- 厚度均匀性控制技术
- 适用无铅制程
- 优异的尺寸稳定性
- 低膨胀和优异的通孔可靠性

### 应用领域:

小间距/Mini/Micro LED、封装基板、摄像机等。

### Key Features:

- Halogen Free and Tg200°C (DMA)
- High whiteness and high reflectivity
- Excellent yellowing resistance
- Thickness uniformity control technology
- Lead free process compatible
- Excellent dimensional stability
- Low Z-axis CTE and excellent through hole reliability

### Applications:

Small space/Mini/Micro LED, Package substrate, VCR, etc.

## 1、General properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	°C	200
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	TMA	ppm/°C	9~10
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA, Before TG	ppm/°C	45
			TMA, After TG	ppm/°C	195
			50~260°C	%	2.2
	288°C 分层时间 T288	2.4.24.1	Clad	min	>60
			Etched	min	>60
	288°C 热冲击 Thermal stress	2.6.8	288°C, solder dip	S	>600
热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	°C	380	
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	>10 <sup>10</sup>
	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	>10 <sup>10</sup>
	Dk (RC50%)	2.5.5.9	1GHz;C-24/23/50	/	5.4

	Df (RC50%)	2.5.5.9	1GHz;C-24/23/50	/	0.019
物理性能 Physical	白度 Whiteness	GB2911982	Internal standard	%	90
	弯曲强度 Flexural Strength	LW CW	2.4.4	A	MPa 550 490
	弯曲模量 Flexural modulus	JB/T 6544-1993	A	GPa	27
	剥离强度 Peel Strength (Hoz Copper Foil)	2.4.8	288°C/10s	N/mm	0.9
	热导率 Thermal conductivity	ASTM-D5470	C-96/35/90	W/(m*k)	0.7
	吸水率 Moisture Absorption	2.6.2.1	D-24/23	%	0.18

Specimen thickness: 0.4mm or 0.8mm. Test Method is according to IPC TM-650.